

Features

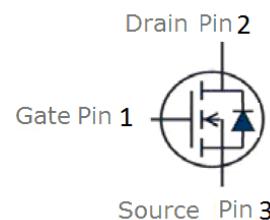
- N-Channel
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5$ V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant

V_{DS}	60	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	5.0	$m\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=4.5$ V	6.0	$m\Omega$
I_D	85	A

TO-252



Part ID	Package Type	Marking	Tape and reel information
VSD007N06MS	TO-252	007N06M	2500pcs/Reel



Maximum ratings, at $T_A = 25^\circ C$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	60	V
V_{GS}	Gate-Source voltage	± 20	V
I_S	Diode continuous forward current	$T_c = 25^\circ C$	A
I_D	Continuous drain current @ $V_{GS}=10V$	$T_c = 25^\circ C$	A
		$T_c = 100^\circ C$	A
I_{DM}	Pulse drain current tested ①	$T_c = 25^\circ C$	A
EAS	Avalanche energy, single pulsed ②	93	mJ
P_D	Maximum power dissipation	$T_c = 25^\circ C$	W
T_{STG}, T_J	Storage and Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.5	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	52.5	$^\circ C/W$

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=250\mu\text{A}$	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_j=25^\circ\text{C}$)	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_j=125^\circ\text{C}$)	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=10\text{V}$, $I_D=30\text{A}$	--	5.0	7.0	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	--	6.0	9.0	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	3485	--	pF
C_{oss}	Output Capacitance		--	370	--	pF
C_{rss}	Reverse Transfer Capacitance		--	275	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=24\text{V}$, $I_D=10\text{A}$, $V_{\text{GS}}=10\text{V}$	--	82	--	nC
Q_{gs}	Gate-Source Charge		--	13	--	nC
Q_{gd}	Gate-Drain Charge		--	17	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}$, $I_D=5\text{A}$, $R_G=6.8\Omega$, $V_{\text{GS}}=10\text{V}$	--	26	--	ns
t_r	Turn-on Rise Time		--	125	--	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	58	--	ns
t_f	Turn-Off Fall Time		--	112	--	ns
Source-Drain Diode Characteristics@ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=30\text{A}$, $V_{\text{GS}}=0\text{V}$	--	0.83	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}$, $I_{\text{sd}}=10\text{A}$, $V_{\text{GS}}=0\text{V}$ $di/dt=100\text{A}/\mu\text{s}$	--	38	--	ns
Q_{rr}	Reverse Recovery Charge		--	44	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by $T_{j\text{max}}$, starting $T_j = 25^\circ\text{C}$, $L = 0.3\text{mH}$, $R_G = 25\Omega$, $I_{\text{AS}} = 25\text{A}$, $V_{\text{GS}} = 10\text{V}$. Part not recommended for use above this value
- ③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.



Vanguard
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VSD007N06MS

60V/85A N-Channel Advanced Power MOSFET

Typical Characteristics

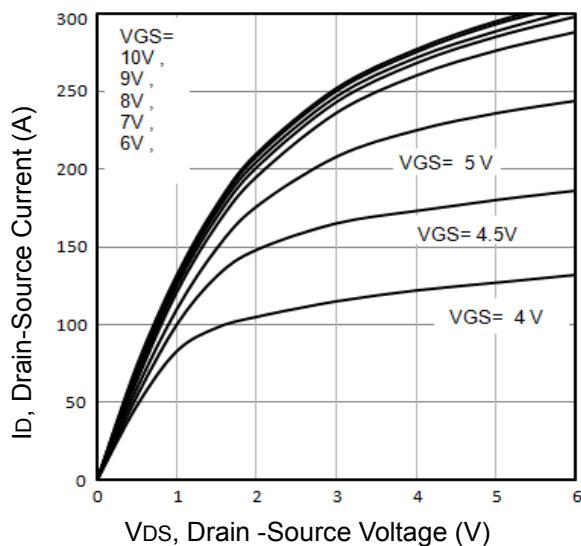


Fig1. Typical Output Characteristics

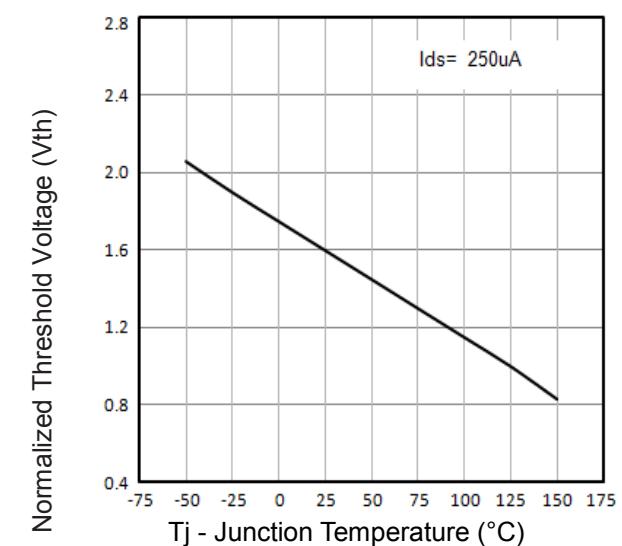


Fig2. Normalized Threshold Voltage Vs. Temperature

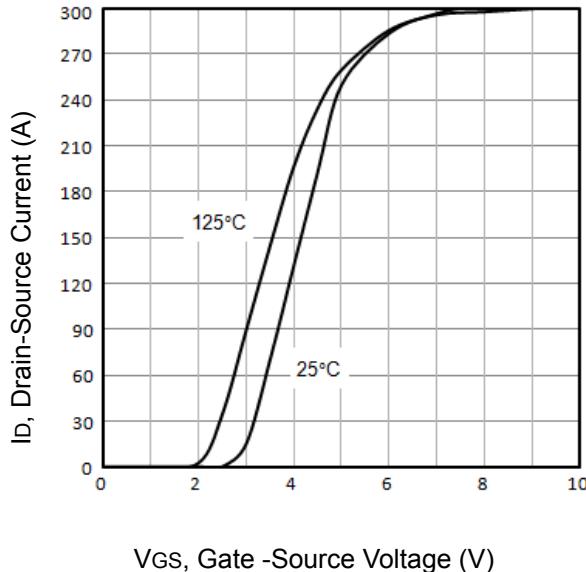


Fig3. Typical Transfer Characteristics

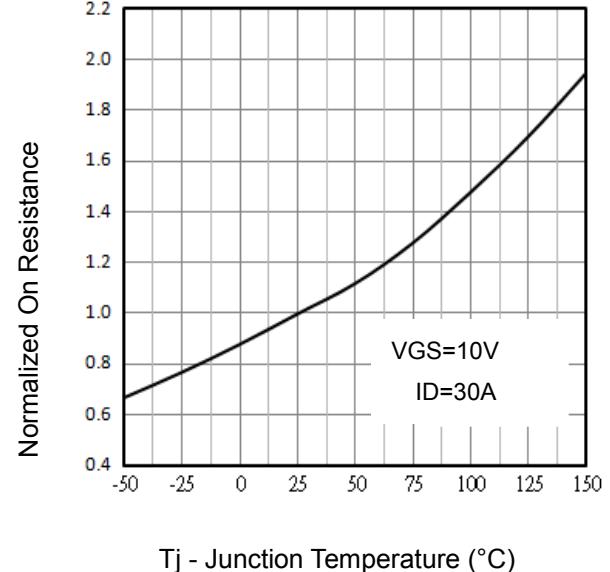


Fig4. Normalized On-Resistance Vs. Temperature

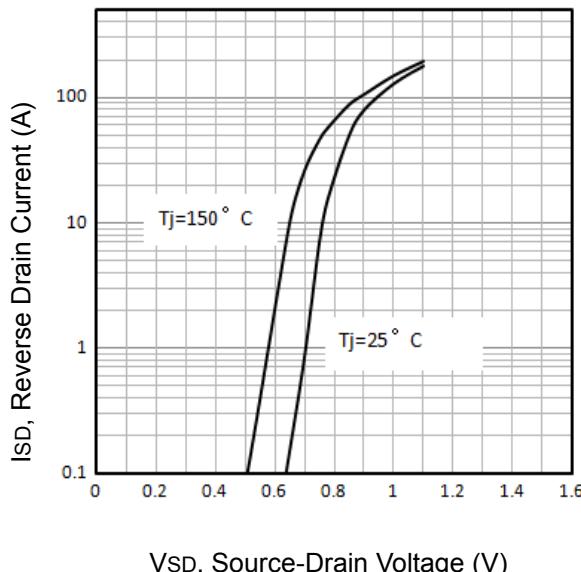


Fig5. Typical Source-Drain Diode Forward Voltage

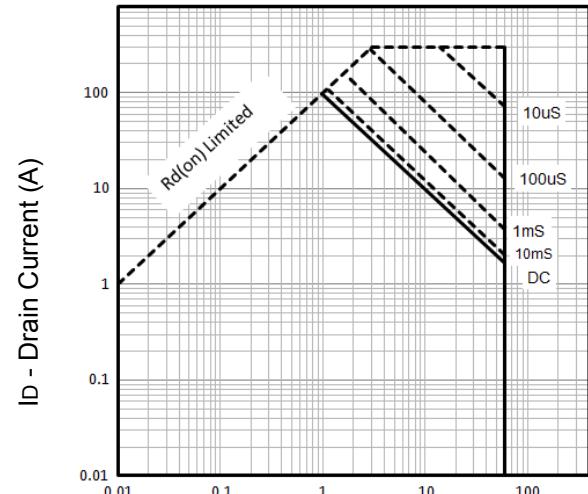


Fig6. Maximum Safe Operating Area



Typical Characteristics

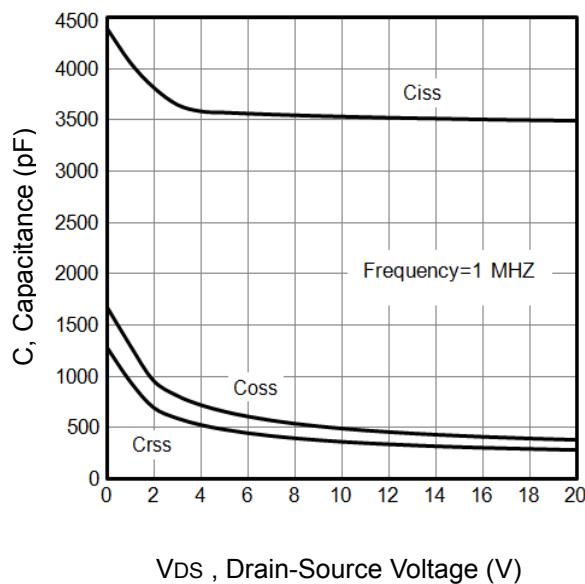


Fig7. Typical Capacitance Vs.Drain-Source Voltage

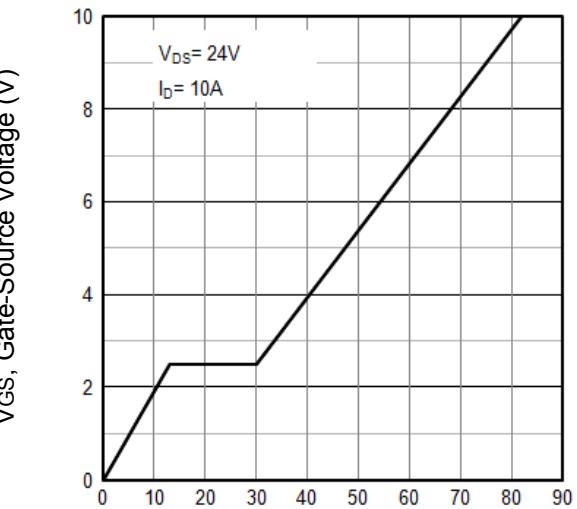


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

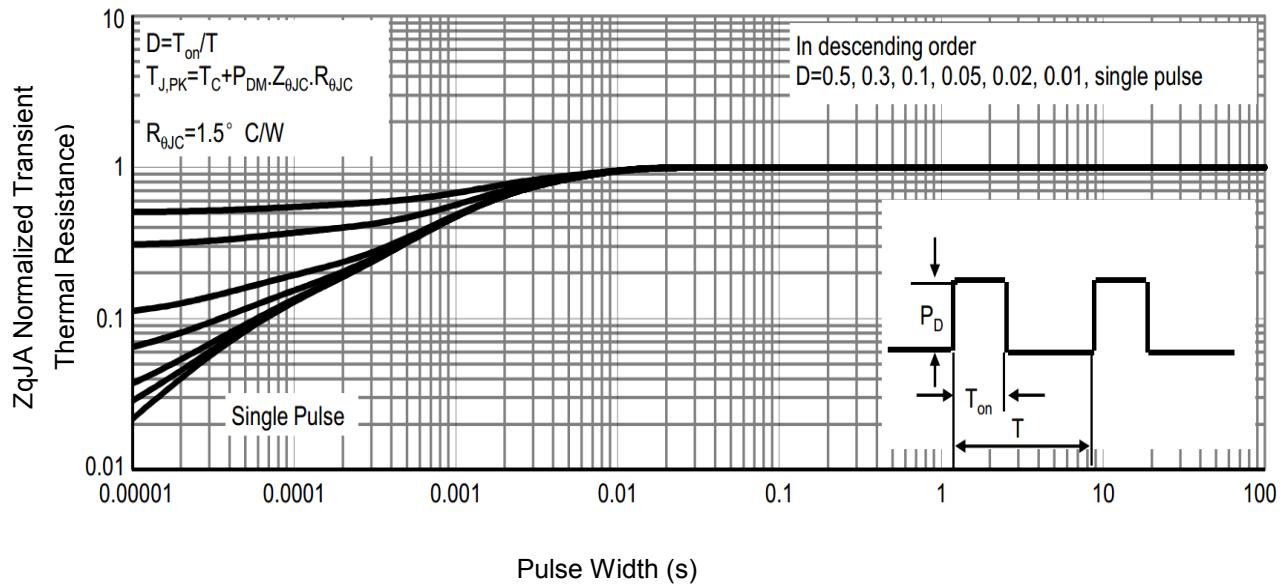


Figure 9: Normalized Maximum Transient Thermal Impedance

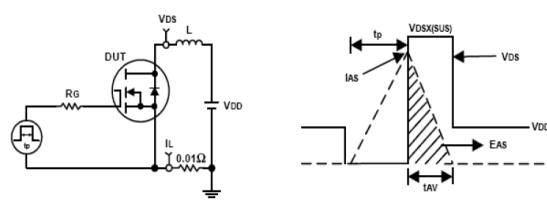


Fig10. Unclamped Inductive Test Circuit and waveforms

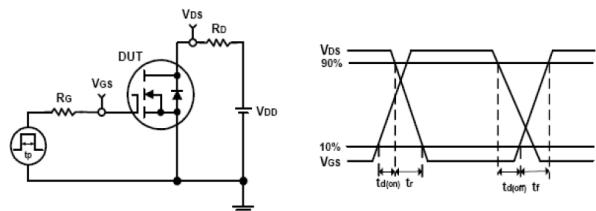


Fig11. Switching Time Test Circuit and waveforms

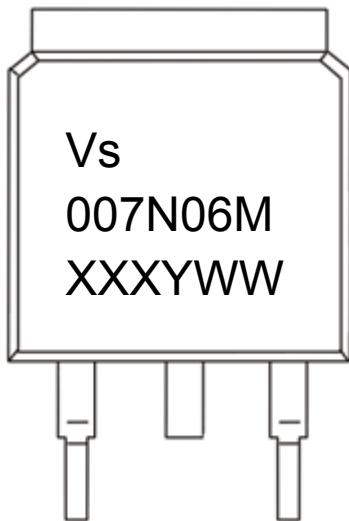


Vanguard
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VSD007N06MS

60V/85A N-Channel Advanced Power MOSFET

Marking Information



1st line: Vanguard Code (Vs)

2nd line: Part Number (007N06M)

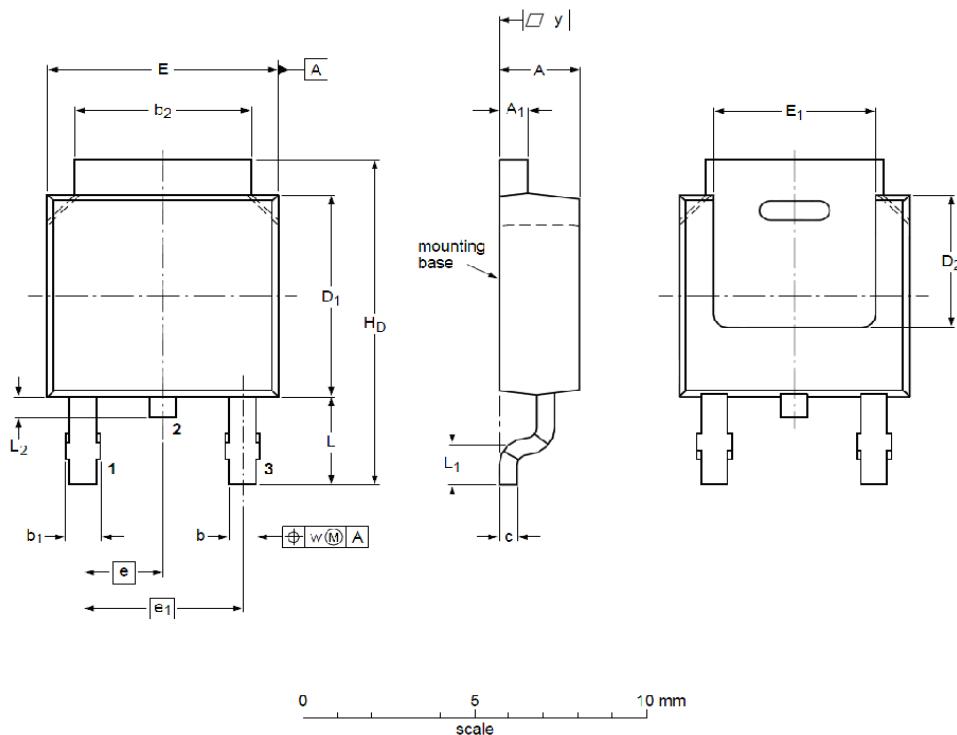
3rd line: Date code (XXXYWW)

XXX: Wafer Lot Number Code , code changed with Lot Number

Y: Year Code, (e.g. E=2017, F=2018, G=2019, H=2020, etc)

WW: Week Code (01 to 53)

TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b₁	0.90	0.98	1.10
b₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D₁	5.98	6.05	6.22	D₂	--	4.00	--
E	6.47	6.60	6.73	E₁	5.10	5.28	5.45
e	--	2.28	--	e₁	--	4.57	--
H_D	9.60	10.08	10.40	L	2.75	2.95	3.05
L₁	--	0.50	--	L₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

Customer Service

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